

Tputty™ 504 Series

Innovative **Technology** for a **Connected** World



SOFT, SILICONE GEL

Tputty[™] 504 is a soft silicone gel thermal gap filler ideal for applications where large gap tolerances are present.

The silicone gel is filled with a complex matrix of ceramic fillers to yield superior thermal performance.

Tputty[™] 504 is soft and compliant transferring little to no pressure between interfaces. Because Tputty[™] 504 has a higher viscosity than grease, it eliminates the bleed and pump-out usually associated with grease. Bond line variances can also be more easily controlled than with traditional thermal pads.

Tputty[™] 504 can be applied like grease and is easily dispensable from a wide range of commercially available equipment including screen print, syringe and automated equipment.

FEATURES AND BENEFITS

- Soft and compliant transferring little to no pressure between interfaces
- 1.8 W/mK thermal conductivity
- Available in 10cc, 30cc and 55cc syringes
- Available in 100cc, 170cc and 305cc auto dispense cartridges
- Available in bulk containers from sample jars through 20 kg pails
- Applies like grease and is easily dispensable from a wide range of commercially available equipment including screen print, syringe and automated equipment

APPLICATIONS

- Flip chip microprocessors
- PPGAs, micro BGAs, BGAs
- DSP chips, graphic accelerator chips
- Other high-wattage electronic components
- LED lighting

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Tputty™ 504	TEST METHOD
Ceramic-filled dispensable silicone gel	
Light Grey	Visual
4,000,000 to 8,000,000	
-45°C to 200°C	
1.8 W/mK	ASTM D5470
2.7 g/cc	
0.15°C-in²/W (0.97°C-cm²/W)	ASTM D5470 (modified)
0.27°C-in²/W (1.74°C-cm²/W)	ASTM D5470 (modified)
500 VAC/mil	ASTM D149
>10 ¹⁴ ohm-cm	ASTM D2240
Available upon request	
0.34 / 0.92	ASTM E595
0.09 / 0.24	ASTM E595
	Ceramic-filled dispensable silicone gelLight Grey $4,000,000$ to $8,000,000$ $-45^{\circ}C$ to $200^{\circ}C$ 1.8 W/mK 2.7 g/cc $0.15^{\circ}C-in^2/W$ $(0.97^{\circ}C-cm^2/W)$ $0.27^{\circ}C-in^2/W$ $(1.74^{\circ}C-cm^2/W)$ 500 VAC/mil $>10^{14}$ ohm-cmAvailable upon request $0.34 / 0.92$

Data for design engineer guidance only. Observed performance varies in application. Engineers are reminded to test the material in application.

THR-DS-Tputty-504 1111

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